

# N-Channel Enhancement Mode MOSFET

## 1. Product Information

### Features

SGT technology

Excellent  $R_{DS(ON)}$

Low gate charge

### Applications

DC/DC Converter

LED Backlighting

Power Management Switches

### Quick reference

$V_{DS} = 100V$

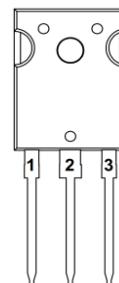
$I_D = 220A$

$R_{DS(ON)} < 2.8m\Omega$  @  $V_{GS} = 10 V$  (Type:  $2.1m\Omega$ )

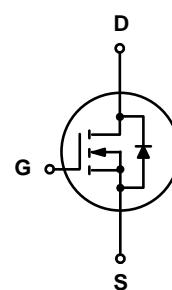
### Pin Description

Pin	Description
1	Gate(G)
2	Drain(D)
3	Source(S)

### Simplified Outline



### Symbol



Top View  
TO-247-3L

## Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape width	Quantity	
KJ220N10P	TO-247-3L	220N10 XXXXYY	XXXXYY: Date Code	-	-	1000

## 2. Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Values	Unit
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current, $V_{GS}@10V$	220	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current, $V_{GS}@10V$	180	A
$I_{DM}$	Pulsed Drain Current	840	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	500	mJ
$I_{AS}$	Avalanche Current	106.8	A
$P_D @ T_c=25^\circ C$	Power Dissipation <sup>4</sup>	296	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55~150	°C
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	0.42	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case	40	°C/W

**3. Electrical Characteristics** ( $T_C=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	100	-	-	V
$I_{GSS}$	Gate-body Leakage current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current, $T_J=25^\circ\text{C}$	$V_{DS}=100\text{V}$ , $V_{GS}=0\text{V}$	-	-	1	$\mu\text{A}$
$I_{DSS}$	Zero Gate Voltage Drain Current, $T_J=100^\circ\text{C}$		-	-	100	
$V_{GS(th)}$	Gate-Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	2.0	2.9	4.0	V
$R_{DS(on)}$	Drain-Source on-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=20\text{A}$	-	2.1	2.8	$\text{m}\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}$ , $V_{DS}=50\text{V}$ , Frequency=1MHz	-	8800	-	pF
$C_{oss}$	Output Capacitance		-	1290	-	
$C_{rss}$	Reverse Transfer Capacitance		-	40	-	
$R_g$	Total Gate Charge	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $f=1\text{MHz}$	-	3.4	-	$\Omega$
$Q_g$	Total Gate Charge	$V_{GS}=10\text{V}$ , $V_{DS}=50\text{V}$ , $I_D=20\text{A}$	-	150	-	nC
$Q_{gs}$	Gate-Source Charge		-	34	-	
$Q_{gd}$	Gate-Drain Charge		-	26	-	
$t_{d(on)}$	Turn-on Delay Time	$V_{GS}=10\text{V}$ , $V_{DS}=50\text{V}$ , $R_g=3\Omega$ , $I_D=20\text{A}$	-	30.8	-	ns
$t_r$	Turn-on Rise Time		-	26	-	
$t_{d(off)}$	Turn-off Delay Time		-	68	-	
$t_f$	Turn-off Fall Time		-	12.4	-	
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$I_F=20\text{A}$ , $V_{GS}=0\text{V}$	-	-	1.2	V
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	-	-	190	A
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=20\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	-	110	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	202	-	nC

**Notes:**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The  $E_{AS}$  data shows Max. rating. The test condition is  $V_{DD}=50\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.4\text{mH}$ ,  $I_{AS}=64\text{A}$
- 4、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

#### 4.Typical Characteristics

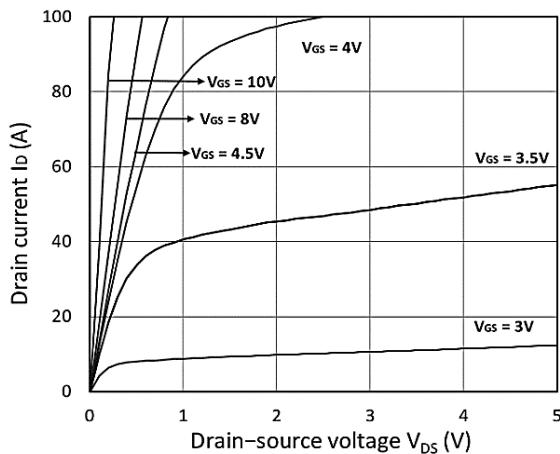


Figure 1. Output Characteristics

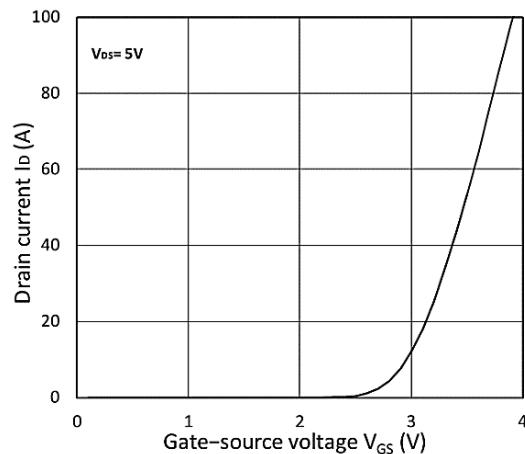


Figure 2. Transfer Characteristics

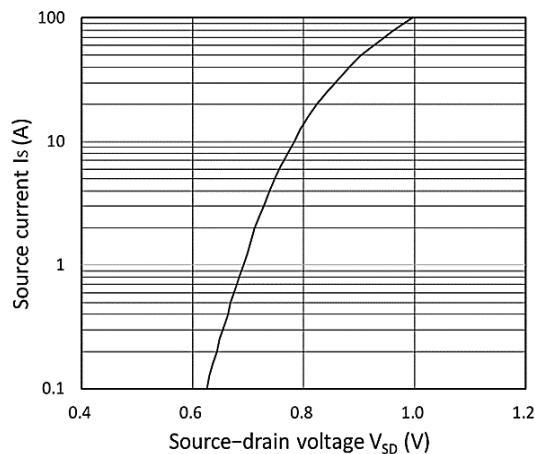


Figure 3. Forward Characteristics of Reverse

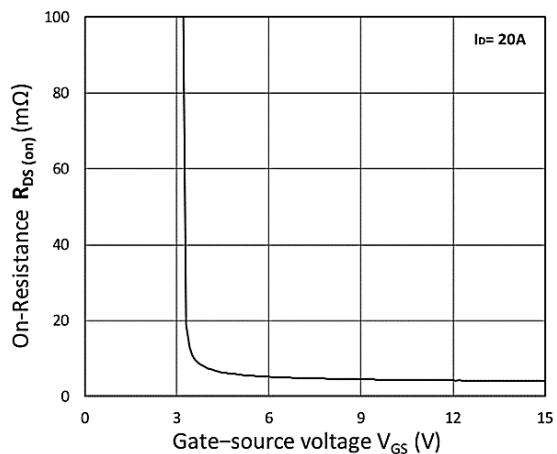


Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$

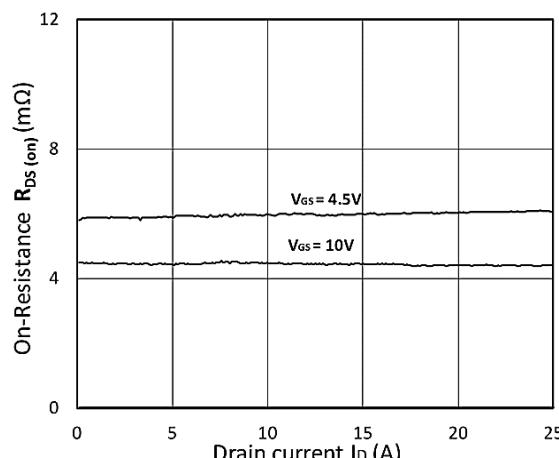


Figure 5.  $R_{DS(ON)}$  vs.  $I_D$

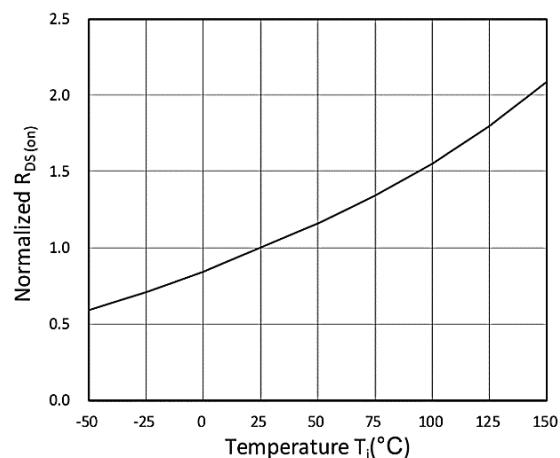
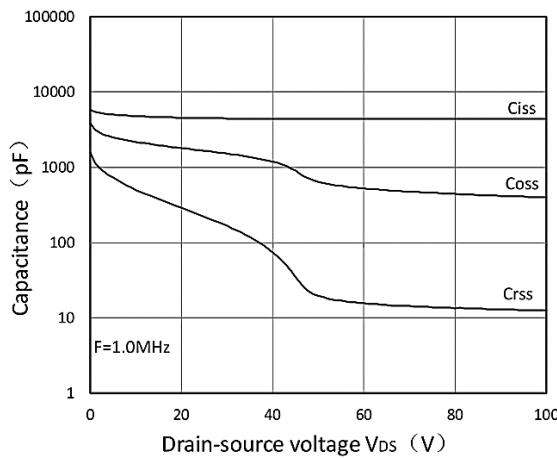
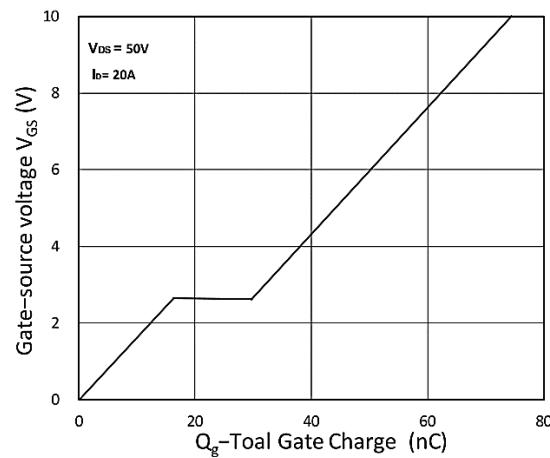


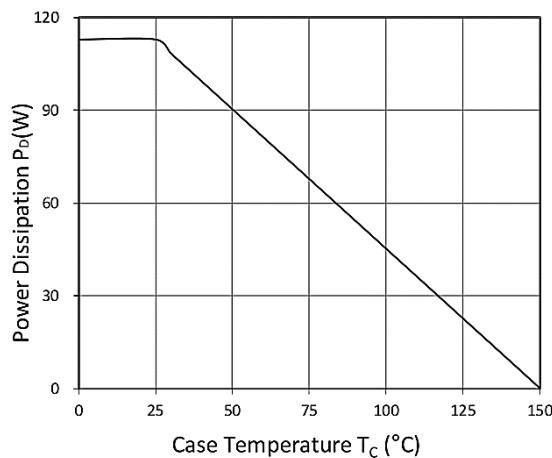
Figure 6. Normalized  $R_{DS(ON)}$  vs. Temperature



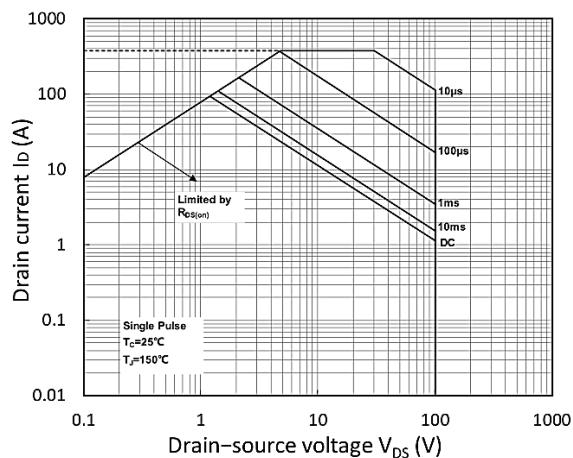
**Figure 7. Capacitance Characteristics**



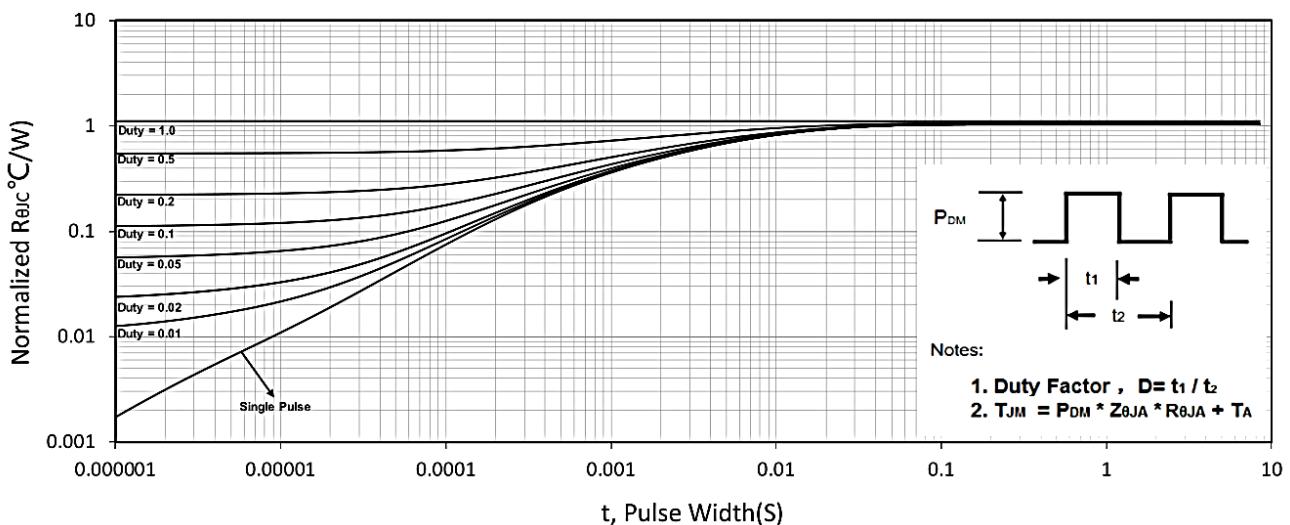
**Figure 8. Gate Charge Characteristics**



**Figure 9. Power Dissipation**



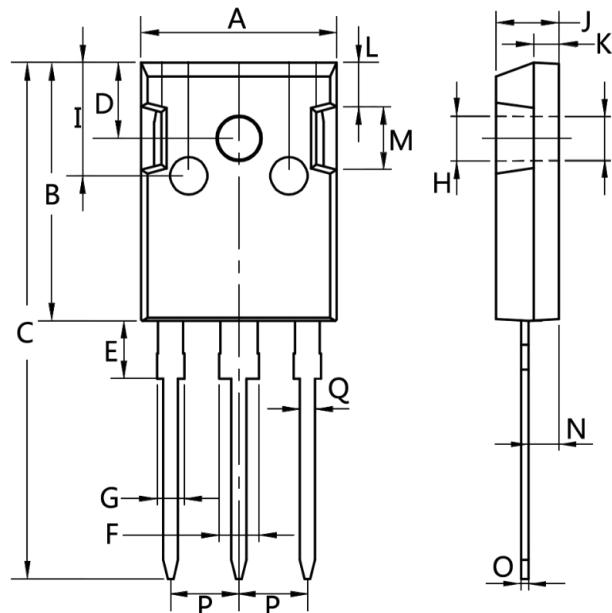
**Figure10. Safe Operating Area**



**Figure 11. Normalized Maximum Transient Thermal Impedance**

## 5.Package Mechanical Data

TO-247-3L



Dim.	Min.	Max.
A	15.0	16.0
B	20.0	21.0
C	41.0	42.0
D	5.0	6.0
E	4.0	5.0
F	2.5	3.5
G	1.75	2.5
H	3.0	3.5
I	8.0	10.0
J	4.9	5.1
K	1.9	2.1
L	3.5	4.0
M	4.75	5.25
N	2.0	3.0
O	0.55	0.75
P	Typ 5.08	
Q	1.2	1.3